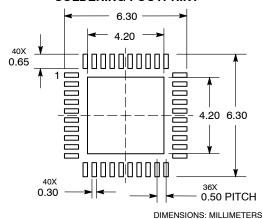


## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **DATE 18 APR 2007**

## NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSIONS: MILLIMETERS.
- DIMENSION 6 APPLIES TO PLATED
  TERMINAL AND IS MEASURED BETWEEN
- 0.25 AND 0.30mm FROM TERMINAL COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
А3	0.20 REF		
b	0.18	0.30	
D	6.00 BSC		
D2	4.00	4.20	
Е	6.00 BSC		
E2	4.00	4.20	
е	0.50 BSC		
L	0.30	0.50	
K	0.20		

## **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

I DOCHMENT NUMBER I COLOMOLIZACED I		Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	' '	
Γ	DESCRIPTION:	QFN40, 6 x 6 x 0.85, 0.5 MM PITCH		PAGE 1 OF 1

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